

Date Created : 2007/11/27
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PCN# : Q4074805

FORECAST CHANGE NOTIFICATION

This is to inform you that a design and/or process change will be made to the following product(s). This notification is for your information and concurrence. This is a preliminary notification. A Final PCN will be issued when qualification is complete and data is available.

If you require data or samples to qualify this change, please contact **Fairchild Semiconductor within 30 days of receipt of this notification.**

If you have any questions concerning this change, please contact:

Technical Contact:

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PCN Originator:

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Implementation of change:

Expected 1st Device Shipment Date: 2008/03/04

Earliest Year/Work Week of Changed Product: 0810

Change Type Description: Alternate Fab Location, Metallization Material

Description of Change (From): Selected Mosfet products currently manufactured using the 8-inch line in Mountain Top, PA. The backmetal for the affected products is being changed from 5KA, 3KA, 3.5KA, 20KA (AL-Ti-Ni-Ag).

Description of Change (To): Selected Mosfet devices currently fabricated at Fairchild Semiconductor 8-inch line in Mountain Top, PA, USA will be also manufactured at Advanced Semiconductor Manufacturing Corporation (ASMC), the 6-inch facility for wafer fabrication located in Shanghai, China. The backmetal of these selected devices is being changed to 3KA, 2KA, 10KA (Ti-Ni-Ag). The new backmetal, Ti-Ni-Ag, is a standard backmetal system used on other qualified MOSFET products. There will be no additional change to the die layout, die size, geometry, substrate, device specification, performance and function of any affected devices. Quality and reliability will remain at highest standard.

Reason for Change : Advanced Semiconductor Manufacturing Corporation (ASMC) will be an alternate fabrication site for the devices listed in the FSID list. This will allow Fairchild Semiconductor to be able to respond to increased demand quickly and reduce cycle time.

Qual/REL Plan Numbers : Q20070478

Qualification :

To qualify the Advanced Semiconductor Manufacturing Corporation (ASMC) 6-inch wafer fab for processing of existing high voltage products in TO220, TO247, TO251, TO252, TO262, TO263, and XSWFR packages. Qualification testing will be using 2 test vehicles from the planar UltraFET 100 volt devices, namely HUF75652G3 in TO247 package, and HUF75645S3S in D2PAK package, each using 3 fab lots.

Qualification Stress Test and Sample Size Detail

Device #1	HUF75645S3S
Package:	TO263
#Leads:	002

Precondition Description:

				Read-points	Sample		
Stress	P/C	Standard	Conditions		A	B	C
PCNL1A		JESD22-A113			0	0	0

Environment Stress Detail:

				Readpoints			Samples		
Stress	P/C	Standard	Conditions	TP1	TP2	TP3	A	B	C
ACLV	X	JESD22-A102	100%RH, 121C	96			77	77	77
H3TRB	X	JESD22-A101B	85%RH, 85C, 80V	168	500	1000	77	77	77
HTGB		JESD22-A108	175C, 20V	168	500	1000	77	77	77
HTRB		JESD22-A108	175C, 80V	168	500	1000	77	77	77
PRCL1	X	MIL-STD-750 M1037	Delta 100C, 3.5 Min On/Off	4000	8572		77	77	77
TMCL1	X	JESD22-A104	-55C, 150C	500	1000		77	77	77

Device #2	HUF75652G3
Package:	TO247
#Leads:	003

Environment Stress Detail:

				Readpoints			Samples		
Stress	P/C	Standard	Conditions	TP1	TP2	TP3	A	B	C
ACLV		JESD22-A102	100%RH, 121C	96			77	77	77
H3TRB		JESD22-A101B	85%RH, 85C, 80V	168	500	1000	77	77	77
PRCL1		MIL-STD-750 M1037	Delta 100C, 3.5 Min On/Off	5000	8572		77	77	77
TMCL1		JESD22-A104	-55C, 150C	500	1000		77	77	77

Product Id Description : Fairchild Semiconductor's selected HUFxxxx, RFPxxxx, RFDxxxx, and PCFxxxx high voltage products currently manufactured using Fairchild's 8-inch wafer fab located in Mountain Top, PA. Please refer to the Affected FSID section for part number listing.

Affected FSIDs :

HUF75307D3	HUF75307D3ST	HUF75309D3S
HUF75309D3ST	HUF75309P3	HUF75332P3
HUF75332S3ST	HUF75337P3	HUF75337S3S
HUF75343S3ST	HUF75542P3	HUF75545P3
HUF75545S3	HUF75545S3S	HUF75545S3ST
HUF75545S3ST_F101	HUF75631P3	HUF75631S3S
HUF75631S3ST	HUF75637P3	HUF75637S3S
HUF75637S3ST	HUF75637S3_NR4895	HUF75639G3
HUF75639P3	HUF75639P3_F102	HUF75639S3
HUF75639S3S	HUF75639S3ST	HUF75645P3
HUF75645S3S	HUF75645S3ST	HUF75645S3ST_F101

HUF75645S3ST_F102	HUF75652G3	HUF76407D3
HUF76407D3S	HUF76407D3ST	HUF76407P3
HUF76419D3	HUF76419D3ST	HUF76419P3
HUF76419S3ST	HUF76423D3	HUF76423D3S
HUF76423P3	HUF76429D3S	HUF76429D3ST
HUF76429P3	HUF76429S3ST	HUF76439S3S
HUF76439S3ST	HUF76445P3	HUF76445S3S
HUF76609D3	HUF76609D3S	HUF76609D3ST
HUF76629D3	HUF76629D3S	HUF76629D3ST
HUF76639P3	HUF76639S3S	HUF76639S3ST
HUF76645P3	HUF76645S3S	HUFA75645S3S
HUFA75652G3	HUFA76429D3	HUFA76429D3S
HUFA76429D3ST	HUFA76429P3	PCF40N10W
RFD12N06RLE	RFD12N06RLESM9A	RFD14N05L
RFD14N05LSM	RFD14N05LSM9A	RFD16N05LSM
RFD16N05LSM9A	RFD16N06LESM9A	RFD3055LE
RFD3055LESM	RFD3055LESM9A	RFP12N10L
RFP14N05L	RFP22N10	RFP3055LE
RFP30N06LE	RFP40N10	RFP40N10_F102
RFP50N05L	RFP70N06	